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|---|---|---|---|---|---|
| **池州华宇电子科技股份有限公司**<br>**CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD** | 客户代码<br>Customer No. | 1298 | 线图号<br>Drawing No. | HY-PX-1298-001 A | 页码 Page<br>1 / 7 |
| 焊线图纸 Bonding Diagram | 产品名称<br>Product Type | Z42M | 封装外型<br>PKG Type | FBGA200B(14.5X10x1.1-P0.65) | |

工程验证

主要材料/BOM 清单信息(Information of Material/BOM list)：

| **Material** | | | customer Part No. | **Part No.** | **Dimension** | **Note** |
|---|---|---|---|---|---|---|
| 1 | 基板 | FBGA200B(145100)1298001 | / | / | 240X76.3X0.18 | 深圳和美精艺 |
| 2 | 晶圆 | Z42M | / | / | 7948*6476*60 | 3 inch tray |
| 3 | DAF膜 | 来料 | / | / | / | / |
| 4 | 线材 | Au 16 | / | / | 0.65mil | 深圳若榆半导体材料科技有限公司 |
| 5 | 塑封料 | EME-G750N Type B | / | / | fillsize 55um,密度1.99 | 住友电木 |
| 6 | 植球助焊剂 | WF-6317P | / | / | / | / |
| 7 | 植球 | SAC305 | / | / | 0.35 MM | 千纳成 |

| 履历 | | |
|---|---|---|
| 序号 | 内容 | 日期 |
| 1 | 新发行 | 2025.11.25 |
| 2 | 增加键合局部放大示意图 | 2025.11.29 |

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|---|---|---|---|---|---|---|
| 拟制<br>Prepared by | NINGLIN | 制图日期<br>Create Date | 2025/11/29 | 生效日期<br>Effective Date | | 客户确认签字/盖章:<br>Customer Signature |
| 研发审核<br>R&d check | | 产品工程审核<br>Product engineering check | | 批准<br>Approved by | | |

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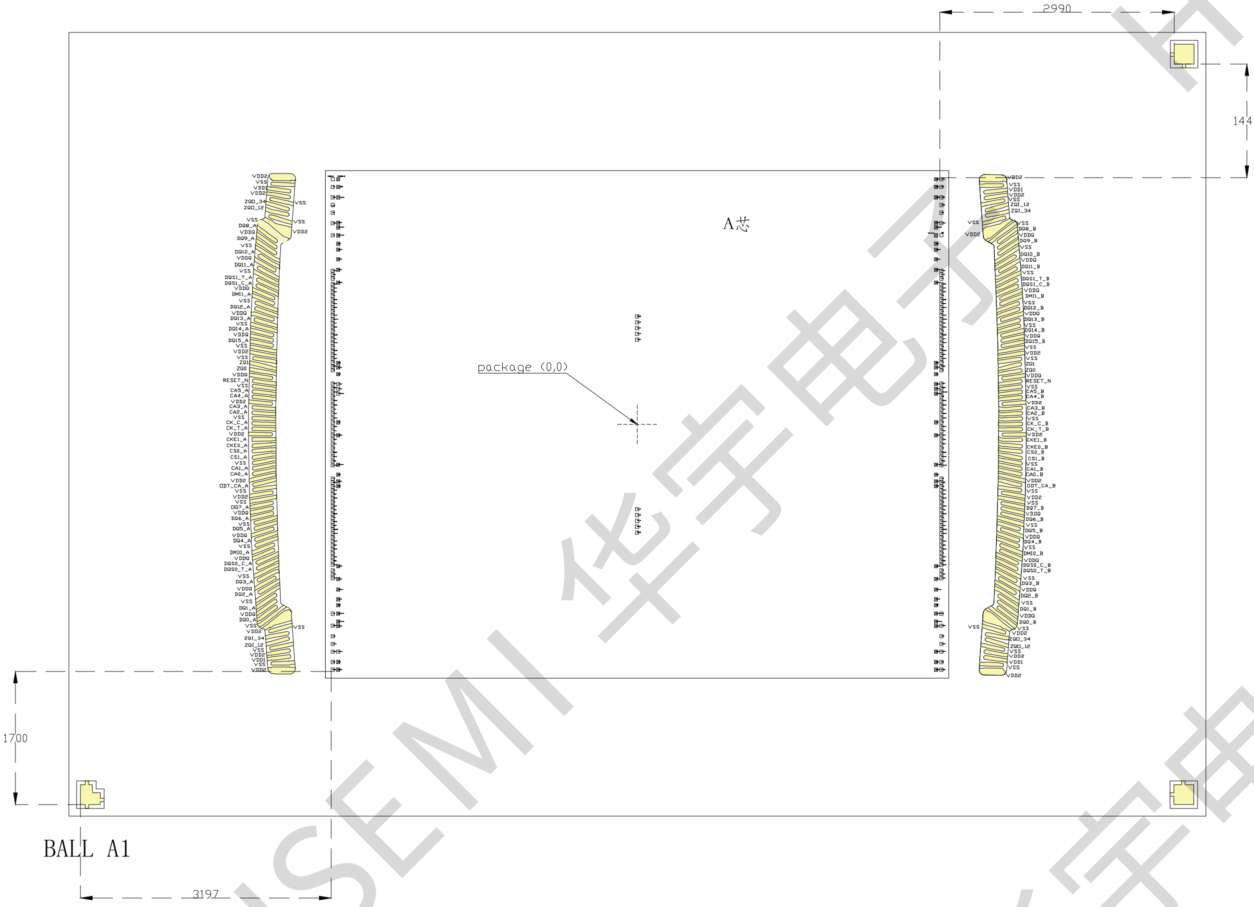
| | 产品名称<br>Product Type | Z42M | 封装外型<br>PKG Type | FBGA200B(14.5X10x1.1-P0.65) | |

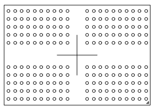
# 装片示意：

工程验证



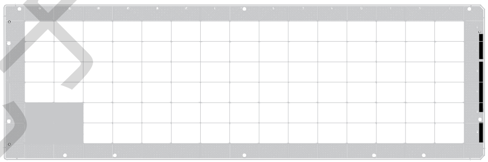
注意：

1. 装片方向见附页3



底部示意图

框架传送方向（装片）：
L/F Direction（D/A）：（三圆孔朝上）



实物图：
Chip photo：

特殊说明 Special Instructions：

注意：DB装片精度±25um。

| 说明<br>Instructions | 粘片胶类型<br>epoxy type | 芯片名称<br>Die name | 芯片尺寸<br>Die Size | 最小焊盘尺寸<br>Min BPO (µm²) | 最小焊盘间距<br>Min BPP(µm) | 铝垫厚度(µm)<br>Pad Thickness | 焊盘下是否有电路<br>Circuit under Pad | 划片道宽度<br>Street line (µm) | 晶圆尺寸<br>Wafer Size | 是否激光切割<br>If laser ? | 减薄厚度<br>(µm)<br>Wafer Thickness |
|---|---|---|---|---|---|---|---|---|---|---|---|
| A芯：<br>DIE A | 来料DAF | Z42M | 7948*6476(µm²)<br>312.9*25.5(mil²) | 42*42 | 69 | / | / | / | / | / | 60 |

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|---|---|---|---|---|---|---|
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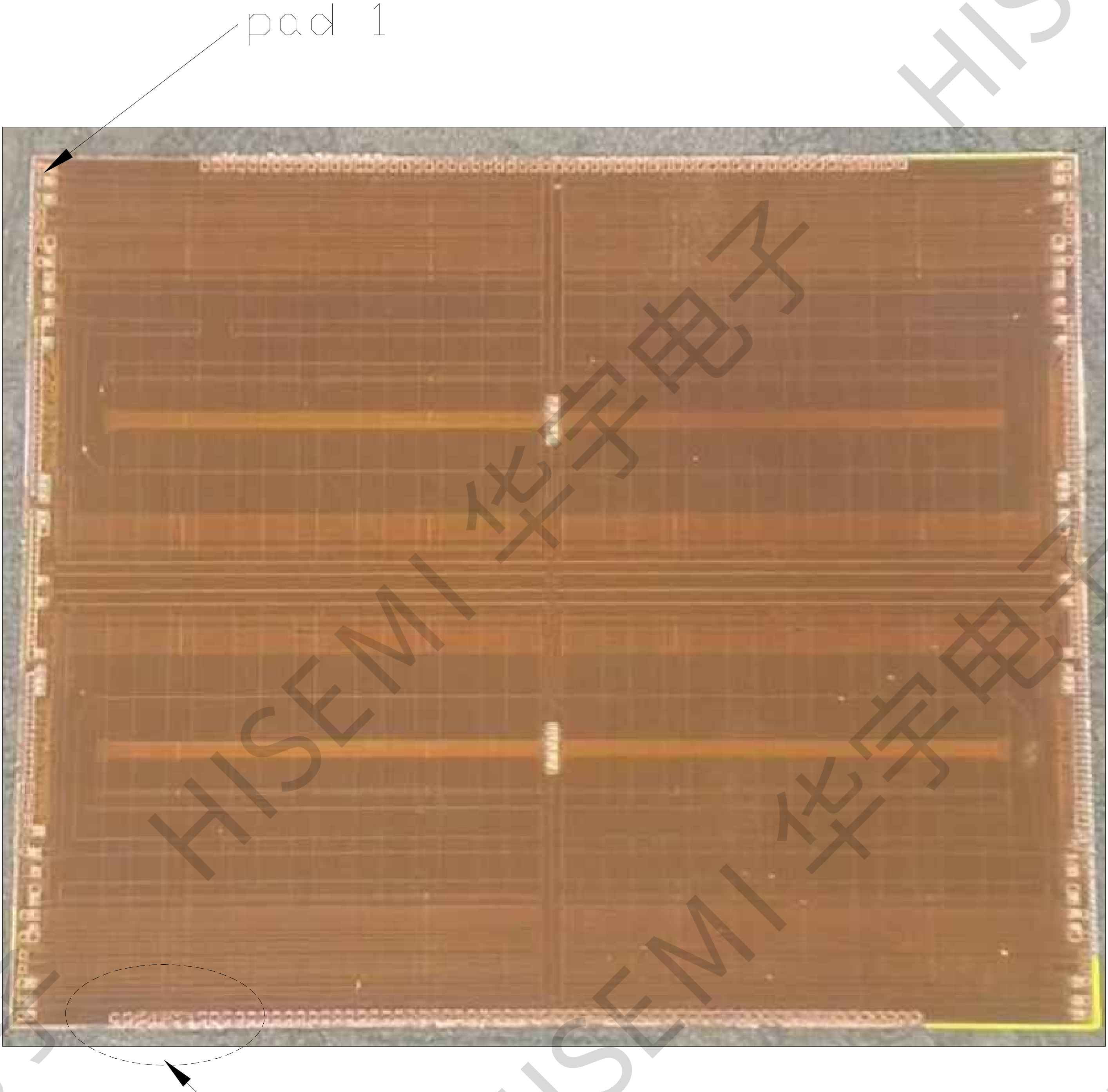
**CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD**
焊线图纸 Bonding Diagram

| | | | | |
|---|---|---|---|---|
| 客户代码<br>Customer No. | 1298 | 线图号<br>Drawing No. | HY-PX-1298-001 A | 页码 Page<br>3 /7 |
| 产品名称<br>Product Type | Z42M | 封装外型<br>PKG Type | FBGA200B(14.5X10x1.1-P0.65) | |

实物方向示意：
（按照此方向装片）

工程验证



注意此处pad更接近芯片短边pad

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| 研发审核<br>R&d check | | 产品工程审核<br>Product engineering check | | 批准<br>Approved by | |

客户确认签字/盖章:
Customer Signature

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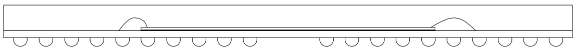
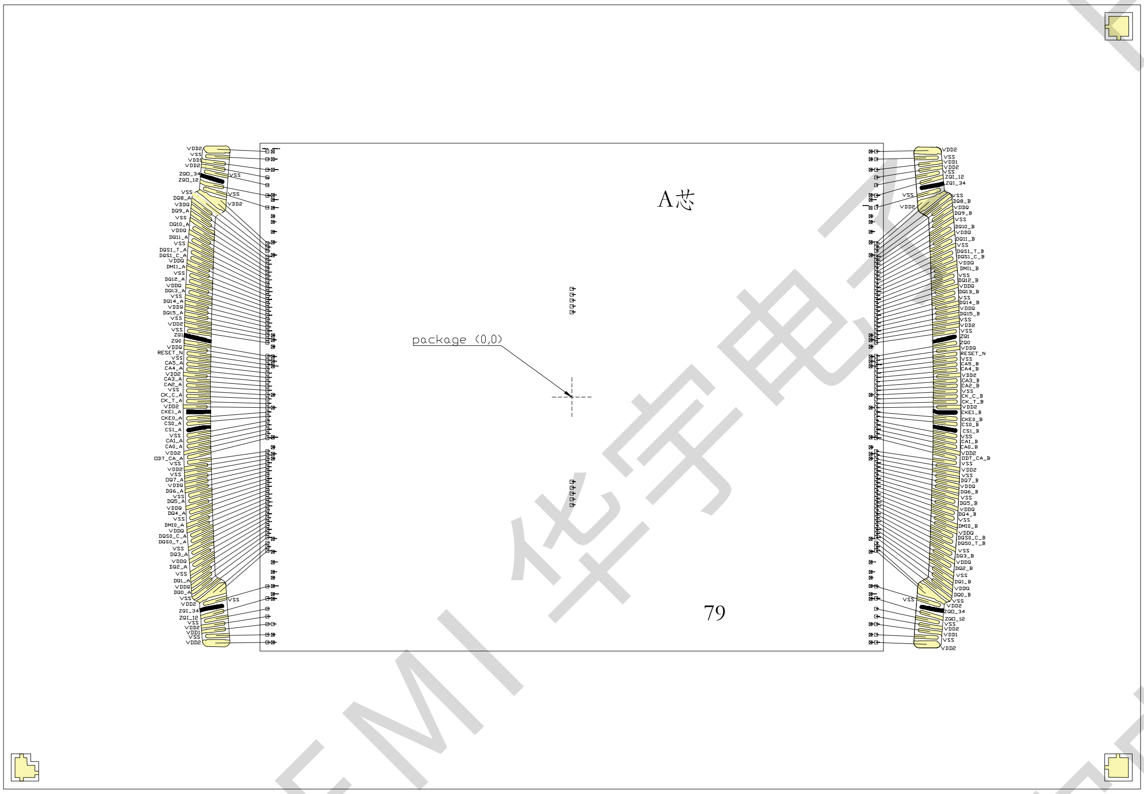
| | 产品名称<br>Product Type | Z42M | 封装外型<br>PKG Type | FBGA200B(14.5X10x1.1-P0.65) | |

| 焊线种类<br>Wire Type | 焊线直径(μm)<br>Wire Diameter | 焊线根数<br>NO. of wire | 焊线总长(μm)<br>Total wire length | 最长线长(μm)<br>Longest wire length | 最短线长(μm)<br>Shortest wire length | 塑封料型号(绿色环保)<br>Compound Type (Green) | 基板编码<br>Substrate No. |
|---|---|---|---|---|---|---|---|
| 金丝<br>Au | 16 | 172 | 205529 | 1052 | 636 | 首选(Preferred)：EME-G750N TYPE B<br>备选(Optional)： | FBGA200B(145100)1298001 |
| 客户图号<br>Customer drawing NO. | | | | | | | |

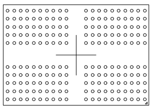
键合示意：



工程验证



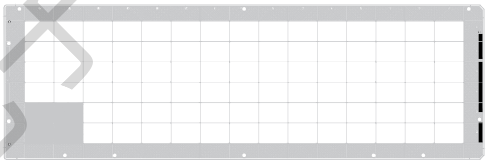
BALL A1



BALL A1

底部示意图

| 框架传送方向（装片）：<br>L/F Direction（D/A）：(三圆孔朝上) | 实物图：<br>Chip photo： | 特殊说明 Special Instructions：<br>注意：数字为不打线pad个数。 |
|---|---|---|



| 说明<br>Instructions | 粘片胶类型<br>epoxy type | 芯片名称<br>Die name | 芯片尺寸<br>Die Size | 最小焊盘尺寸<br>Min BPO (μm²) | 最小焊盘间距<br>Min BPP(μm) | 铝垫厚度(μm)<br>Pad Thickness | 焊盘下是否有电路<br>Circuit under Pad | 划片道宽度<br>Street line (μm) | 晶圆尺寸<br>Wafer Size | 是否激光切割<br>If laser ? | 减薄厚度(μm)<br>Wafer Thickness |
|---|---|---|---|---|---|---|---|---|---|---|---|
| A芯：<br>DIE A | 来料DAF | Z42M | 7948*6476(μm²)<br>312.9*25.5(mil²) | 42*42 | 69 | / | / | / | / | / | 60 |

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| 研发审核<br>R&d check | | 产品工程审核<br>Product engineering check | | 批准<br>Approved by | | |

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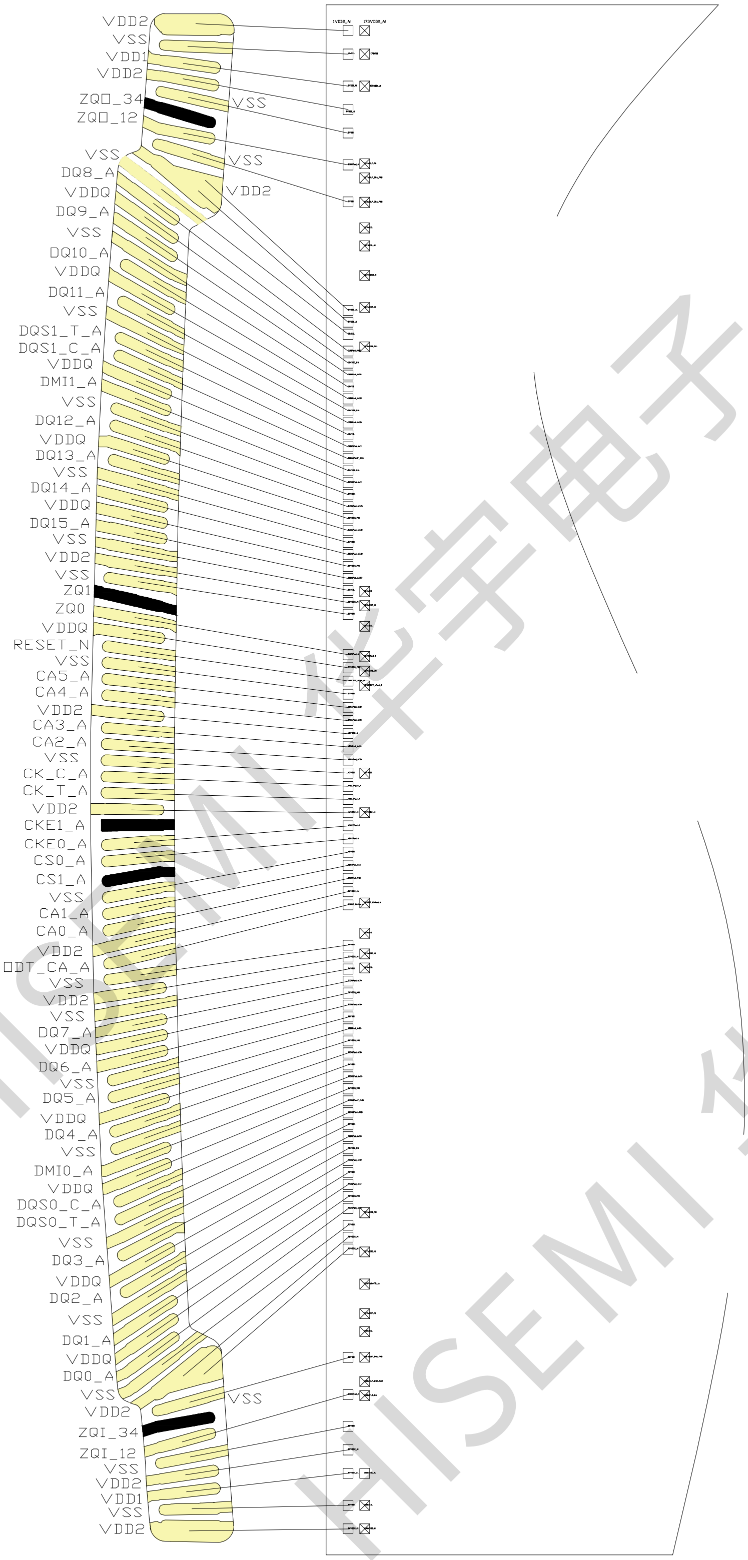
|---|---|---|---|---|---|
| | 产品名称<br>Product Type | Z42M | | 封装外型<br>PKG Type | FBGA200B(14.5X10x1.1-P0.65) |

# 键合示意（左）：

比例：3:1

工程验证



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|---|---|---|---|---|---|---|
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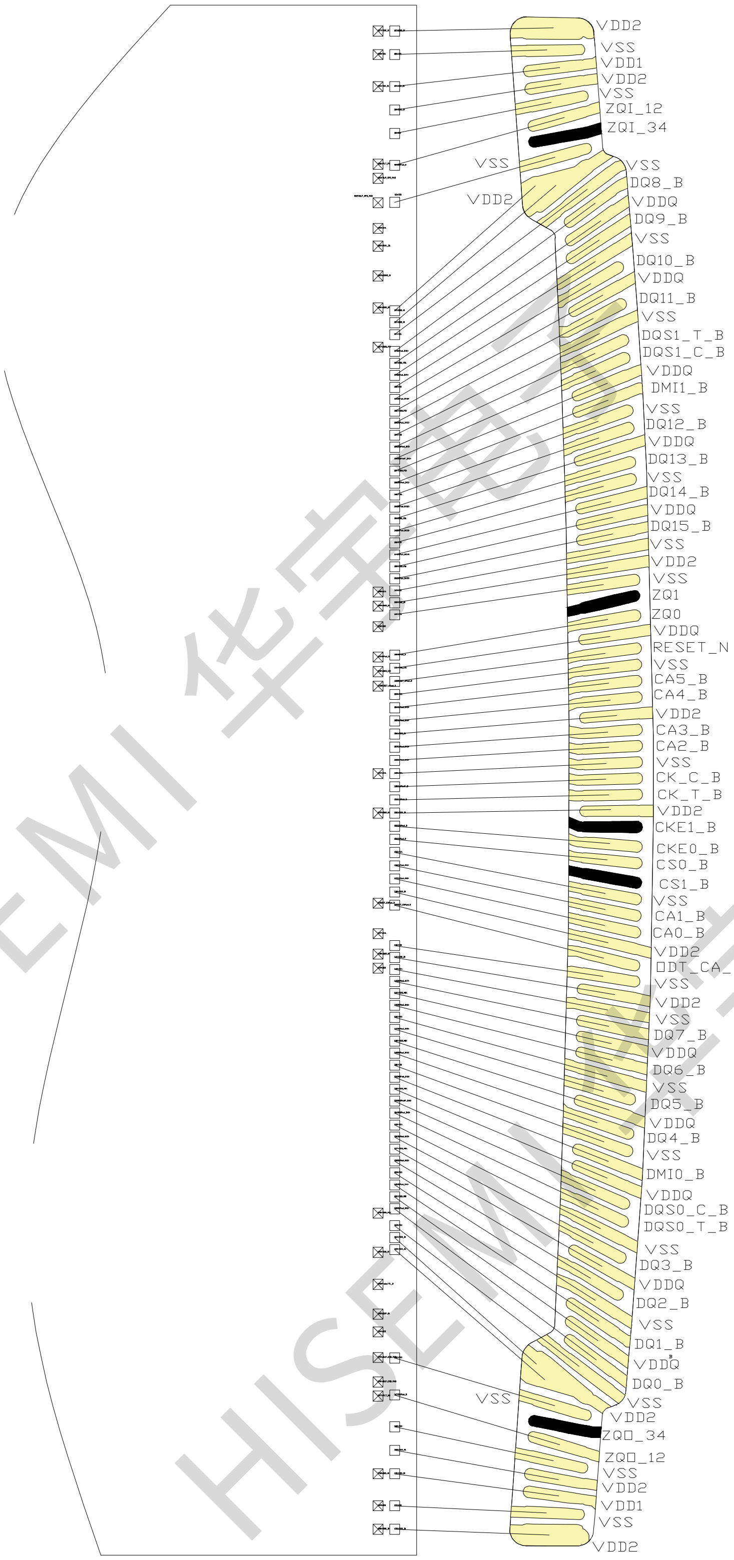
|  | 产品名称<br>Product Type | Z42M |  | 封装外型<br>PKG Type | FBGA200B(14.5X10x1.1-P0.65) |

# 键合示意（右）:

工程验证



|  |  |  |  |  |  |  |
|---|---|---|---|---|---|---|
| 拟制<br>Prepared by | NINGLIN | 制图日期<br>Create Date | 2025/11/29 | 生效日期<br>Effective Date |  | 客户确认签字/盖章:<br>Customer Signature |
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# 焊线图纸 Bonding Diagram

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|---|---|---|---|---|
| 客户代码<br>Customer No. | 1298 | 线图号<br>Drawing No. | HY-PX-1298-001 A | 页码 Page<br>7 /7 |
| 产品名称<br>Product Type | Z42M | 封装外型<br>PKG Type | FBGA200B(14.5X10x1.1-P0.65) | |

工程验证

| | | | | | |
|---|---|---|---|---|---|
| 拟制<br>Prepared by | NINGLIN | 制图日期<br>Create Date | 2025/11/29 | 生效日期<br>Effective Date | 客户确认签字/盖章:<br>Customer Signature |
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